

Jae Hyeong Park

List of Publications by Year in descending order

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210
papers

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times ranked

1262
citing authors

#	ARTICLE	IF	CITATIONS
1	IMCs Microstructure Evolution Dependence of Mechanical Properties for Ni/Sn/Ni Micro Solder-Joints. <i>Materials</i> , 2020, 13, 252.	2.9	2
2	Acoustic Matching Layer Films Using B-Stage Thermosetting Polymer Resins for Ultrasound Transducer Applications. <i>IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control</i> , 2020, 67, 2148-2154.	3.0	8
3	Ultrathin Nanofibrous Membranes Containing Insulating Microbeads for Highly Sensitive Flexible Pressure Sensors. <i>ACS Applied Materials & Interfaces</i> , 2020, 12, 13348-13359.	8.0	69
4	Piezoelectric Ceramics and Flexible Printed Circuits™ Interconnection Using Sn58Bi Solder Anisotropic Conductive Films for Flexible Ultrasound Transducer Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 1897-1903.	2.5	7
5	Bending Properties of Fine Pitch Flexible CIF (Chip-in-Flex) Packages Using APL (Anchoring Polymer) Tj ETQq1 1 0.784314 rgBJ /Overlo		
6	A Study on the Anchoring Polymer Layer (APL) Anisotropic Conductive Films (ACFs) with Self-Exposed Conductive Particles Surface for Ultra-Fine Pitch Chip-on-Glass (COG) Applications. , 2019, , .		0
7	Low Temperature Transient Liquid Phase (TLP) Bonding using Eutectic Sn-In Solder Anisotropic Conductive Films (ACFs) for Flexible Ultrasound Transducer. , 2019, , .		2
8	A study on the resistivity and mechanical properties of modified nano-Ag coated Cu particles in electrically conductive adhesives. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 9171-9183.	2.2	38
9	A Study on the Conductive Particle Movements in Polyvinylidene Fluoride Anchoring Polymer Layer Anisotropic Conductive Films for 20- μm Fine-Pitch Interconnection. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 209-215.	2.5	2
10	Effects of the Curing Properties and Viscosities of Non-Conductive Films (NCFs) on the Sn-Ag Solder Bump Joint Morphology and Reliability. , 2019, , .		3
11	Effects of the Materials Properties of Epoxy Molding Films (EMFs) on Fan-Out Packages (FOPs) Characteristics. , 2019, , .		1
12	Low-Temperature Bonding of PZT (PbZrTiO ₃) and Flexible Printed Circuits Using Sn52In Solder Anisotropic Conductive Films for Flexible Ultrasonic Transducers. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 2152-2159.	2.5	5
13	The Effect of the Thermal Mechanical Properties of Nonconductive Films on the Thermal Cycle Reliability of 40- μm Fine Pitch Cu-Pillar/Ni/SnAg Microbump Flip-Chip Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 10-17.	2.5	1
14	A Study on the Preparation and Properties of Conductive Adhesive Filled with Multi-component Fillers for Green Packaging. , 2018, , .		0
15	A Study on the Optimization of Anisotropic Conductive Films for Sn-3Ag-0.5Cu-Based Flex-on-Board Application at a 250 °C Bonding Temperature. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018, 8, 383-391.	2.5	24
16	The Effect of the SnAg Solder Joint Morphology on the Thermal Cycle Reliability of 40 μm Fine-Pitch Cu-Pillar/SnAg Micro Bump Interconnection. , 2018, , .		1
17	Fabrication and Characterization of Epoxy Molding Films (EMFs) for Wafer-Level and Panel-Level Fan Out Packages. , 2018, , .		5
18	Effects of the Adhesion Strength on the Bending Fatigue Behavior of Cu Pattern Laminated Fabrics Using B-Stage Non-Conductive Films (NCFs). , 2018, , .		1

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19	Effects of ACFs Modulus and Adhesion Strength on the Bending Reliability of CIF (Chip-in-Flex) Packages at Humid Environment. , 2018, , .		3
20	A Study on the Curing Properties and Viscosities of Non-Conductive Films (NCFs) for Sn-Ag Solder Bump Flip Chip Assembly. , 2018, , .		5
21	A Study on the Anchoring Polymer Layer(APL) Solder Anisotropic Conductive Films (ACFs) for Ultra Fine Pitch Flex-on-Flex (FOF) Assembly Using an Ultrasonic Bonding Method. , 2018, , .		1
22	A Study on the Nanofiber-Sheet Anisotropic Conductive Films (NS-ACFs) for Ultra-Fine-Pitch Interconnection Applications. Journal of Electronic Materials, 2017, 46, 167-174.	2.2	9
23	A Study on the Novel Nylon Anchoring Polymer Layer(APL) Anisotropic Conductive Films(ACFs) for Ultra Fine Pitch Chip-on-Glass(COG) Applications. , 2017, , .		0
24	Effects of Anisotropic Conductive Films (ACFs) Gap Heights on the Bending Reliability of Chip-In-Flex (CIF) Packages for Wearable Electronics Applications. , 2017, , .		2
25	The Effect of Anisotropic Conductive Films Adhesion on the Bending Reliability of Chip-in-Flex Packages for Wearable Electronics Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1583-1591.	2.5	21
26	Moisture Effects on NCF Adhesion and Solder Joint Reliability of Chip-on-Board Assembly Using Cu Pillar/Sn-Ag Microbump. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 371-378.	2.5	1
27	Effect of Material Properties of Double-Layer Non Conductive Films (D-NCFs) on the Reflow Reliability of Ultra Fine-Pitch Cu-Pillar/Sn-Ag Micro Bump Interconnection. , 2017, , .		0
28	The Effect of Polymer Rebound on SnBi58 Solder ACFs Joints Cracks during a Thermo-Compression Bonding. , 2017, , .		2
29	A Study on the Fabrication of Electrical Circuits on Fabrics Using Cu Pattern Laminated B-Stage Adhesive Films for Electronic Textile Applications. , 2017, , .		4
30	A Study on the Bonding Conditions and Nonconductive Filler Contents on Cationic Epoxy-Based Sn-Bi Solder ACFs Joints for Reliable Flex-on-Board Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 2087-2094.	2.5	23
31	A Study on the Fine Pitch Flex-on-Flex (FOF) Assembly Using Flux Added Nanofiber Solder Anisotropic Conductive Films (ACFs) and Thermo-Compression Bonding Method. , 2017, , .		0
32	A Study on the Double Layer Non Conductive Films (NCFs) for Fine-Pitch Cu-Pillar/Sn-Ag Micro-Bump Interconnection. , 2016, , .		9
33	Effects of Polymer Ball Size and Polyvinylidene Fluoride Nanofiber on the Ball Capture Rate for 100- μm -Pitch Flex-on-Flex Assembly Using Anisotropic Conductive Films and Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1127-1134.	2.5	7
34	Effects of Cooling Processes and Silica Filler Contents of Solder ACFs (Anisotropic Conductive Films) on the Joints Reliability. , 2016, , .		4
35	Effect of Nanofiber Orientation on Nanofiber Solder Anisotropic Conductive Films Joint Properties and Bending Reliability of Flex-on-Flex Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1317-1329.	2.5	23
36	Effects of PCB Pad Metal Finishes on the Cu-Pillar/Sn-Ag Micro Bump Joint Reliability of Chip-on-Board (COB) Assembly. Journal of Electronic Materials, 2016, 45, 3208-3219.	2.2	6

#	ARTICLE	IF	CITATIONS
37	Effects of ACFs Adhesion on the Bending Reliability of Chip-in-Flex Packages for Wearable Electronics Applications. , 2016, , .		3
38	Joint Morphologies and Failure Mechanisms of Anisotropic Conductive Films (ACFs) During a Power Handling Capability Test for Flex-On-Board Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1820-1826.	2.5	23
39	Thermo-Compression Bonding Using Non-conductive Films (NCFs) for 3-D TSV Micro-Bump Interconnection. , 2016, , .		3
40	A Study on the Cu-Rod Anisotropic Conductive Films (ACFs) for Flex-on-Fabric (FOF) Interconnections Using an Ultrasonic Bonding Method. , 2016, , .		4
41	Bending Properties of Anisotropic Conductive Films Assembled Chip-in-Flex Packages for Wearable Electronics Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 208-215.	2.5	31
42	A Study on the Failure Mechanism and Enhanced Reliability of Sn58Bi Solder Anisotropic Conductive Film Joints in a Pressure Cooker Test Due to Polymer Viscoelastic Properties and Hydroswellling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 216-223.	2.5	33
43	Effects of the Mechanical Properties of Polymer Resin and the Conductive Ball Types of Anisotropic Conductive Films on the Bending Properties of Chip-in-Flex Package. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 200-207.	2.5	15
44	Nanofiber Anisotropic Conductive Films (ACF) for Ultra-Fine-Pitch Chip-on-Glass (COG) Interconnections. Journal of Electronic Materials, 2015, 44, 4628-4636.	2.2	11
45	Effects of Curing Agent and Curing Temperature on Material Properties of Epoxy/BaTiO ₃ Composite Embedded Capacitor Films. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 451-459.	2.5	4
46	Effects of film viscosity on electric field-induced alignment of graphene flakes in B-stage graphene-epoxy composite films. , 2015, , .		0
47	Nanofiber ACFs (anisotropic conductive films) for ultra-fine pitch interconnection. , 2015, , .		0
48	A Study on the Solder Ball Size and Content Effects of Solder ACFs for Flex-on-Board Assembly Applications Using Ultrasonic Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 9-14.	2.5	24
49	Effect of Flux Activators on the Solder Wettability of Solder Anisotropic Conductive Films. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 3-8.	2.5	7
50	Wafer level packages (WLPs) using B-stage non-conductive films (NCFs) for highly reliable 3D-TSV micro-bump interconnection. , 2015, , .		7
51	Ultra-thin chip-in-flex (CIF) technology using anisotropic conductive films (ACFs) for wearable electronics applications. , 2015, , .		5
52	The effects of self-fluxing additives in solder anisotropic conductive films (ACFs) on solder wettability and joint reliability of flex-on-board (FOB) assemblies. , 2014, , .		0
53	A novel double layer NCF for highly reliable micro-bump interconnection. , 2014, , .		13
54	Effect of aligned nanofiber in nanofiber solder anisotropic conductive films (ACFs) on the solder ball movement for flex-on-flex (FOF) assembly. , 2014, , .		1

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55	A study on the fine pitch chip interconnection using Cu/SnAg bumps and B-stage non-conductive films (NCFs) for 3D-TSV vertical interconnection. , 2014, , .		3
56	A novel fine pitch TSV interconnection method using NCF with Zn nano-particles. , 2014, , .		3
57	Analysis of 3D TSV Vertical Interconnection Using Pre-applied Nonconductive Films. Journal of Electronic Materials, 2014, 43, 4214-4223.	2.2	7
58	Effects of pad surface finish on interfacial reliabilities of Cu-pillar/Sn-Ag bumps of 2.5D TSV-enterposer on PCB applications. , 2014, , .		1
59	Warpage Behavior and Life Prediction of a Chip-on-Flex Package Under a Thermal Cycling Condition. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1144-1151.	2.5	1
60	Low-Temperature Curable Photo-Active Anisotropic Conductive Films (PA-ACFs). Journal of Electronic Materials, 2014, 43, 3236-3242.	2.2	3
61	Effect of NCFs with Zn-nanoparticles on the interfacial reactions of 40 um pitch Cu pillar/Sn-Ag bump for TSV interconnection. , 2013, , .		0
62	Low temperature fine pitch Flex-on-Flex (FOF) assembly using nanofiber Sn58Bi solder anisotropic conductive films (ACFs) and ultrasonic bonding method. , 2013, , .		8
63	Effects of ACF Bonding Parameters on ACF Joint Characteristics for High-Speed Bonding Using Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 177-182.	2.5	8
64	Investigation of interfacial phenomena of alloyed Au wire bonding. , 2013, , .		2
65	Effects of nanofiber materials of nanofiber anisotropic conductive adhesives (nanofiber ACAs) for ultra-fine pitch electronic assemblies. , 2013, , .		2
66	Advancing Electronic Packaging Using Microsolder Balls: Making 25-nm Pitch Interconnection Possible. IEEE Nanotechnology Magazine, 2013, 7, 24-30.	1.3	4
67	Fine pitch flex-on-flex (FOF) assembly using nanofiber solder anisotropic conductive films (ACFs) and ultrasonic bonding method. , 2013, , .		0
68	Flux function added solder anisotropic conductive films (ACFs) for high power and fine pitch assemblies. , 2013, , .		11
69	Ultrasonic-Assisted Thermocompression Bonding Method of Solder Anisotropic Conductive Film Joints for Reliable Camera Module Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 2156-2163.	2.5	2
70	Effects of Nanofiber on the Electrical Properties of Anisotropic Conductive Adhesives (ACAs). Journal of Nanoscience and Nanotechnology, 2013, 13, 351-355.	0.9	4
71	Bio-inspired surface treatment on touch screen panels (TSPs) for adhesion enhancement. , 2012, , .		0
72	Vertically aligned nickel nanowire/epoxy composite for electrical and thermal conducting material. , 2012, , .		3

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73	High productivity and damage-free ultrasonic anisotropic conductive film (ACF) bonding for touch screen panel (TSP) assemblies. , 2012, , .		2
74	Low temperature curable anisotropic conductive films (ACFs) with photo-active curing agent (PA-ACFs). , 2012, , .		3
75	A study on the intermetallic growth of fine-pitch Cu pillar/SnAg solder bump for 3D-TSV interconnection. , 2012, , .		2
76	Studies on the Thermal Cycling Reliability of BGA System-in-Package (SiP) With an Embedded Die. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 625-633.	2.5	29
77	Studies on the Polymer Adhesive Wafer Bonding Method Using Photo-Patternable Materials for MEMS Motion Sensors Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1118-1127.	2.5	9
78	Ultrasonic Bonding of Anisotropic Conductive Films Containing Ultrafine Solder Balls for High-Power and High-Reliability Flex-On-Board Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 884-889.	2.5	3
79	Effects of Conductive Particles on the Electrical Stability and Reliability of Anisotropic Conductive Film Chip-on-Board Interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 359-366.	2.5	12
80	Study on Fine Pitch Flex-on-Flex Assembly Using Nanofiber/Solder Anisotropic Conductive Film and Ultrasonic Bonding Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 2108-2114.	2.5	21
81	High performance encapsulant for light-emitting diodes (LEDs) by a sol-gel derived hydrogen siloxane hybrid. Journal of Materials Chemistry, 2012, 22, 7954.	6.7	67
82	Ultrasonic-assisted thermo-compression bonding method for high-performance solder anisotropic conductive film (ACF) joints. , 2012, , .		3
83	Micro-solder/adhesive hybrid joints for high-density, high-power, high-reliability, and reworkable module interconnection in mobile phones. , 2012, , .		3
84	High temperature reliability of Pd-alloyed Au wire/Al bonding interface. , 2012, , .		1
85	Thermally resistant UV-curable epoxy-siloxane hybrid materials for light emitting diode (LED) encapsulation. Journal of Materials Chemistry, 2012, 22, 8874.	6.7	71
86	3D-TSV vertical interconnection method using Cu/SnAg double bumps and B-stage non-conductive adhesives (NCAs). , 2012, , .		7
87	3D-TSV vertical interconnection method using Cu/SnAg double bumps. , 2012, , .		2
88	Ultra low temperature curable anisotropic conductive films (ACFs) with photo latent curing behavior (PLC-ACFs). , 2011, , .		0
89	High-speed flex-on-board assembly method using anisotropic conductive films (ACFs) combined with room temperature ultrasonic (US) bonding for high-density module interconnection in mobile phones. , 2011, , .		7
90	Nanofiber anisotropic conductive adhesives (ACAs) for ultra fine pitch chip-on-film (COF) packaging. , 2011, , .		19

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91	Wafer-Level Packages Using Anisotropic Conductive Adhesives (ACAs) Solution for Flip-Chip Interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 792-797.	2.5	5
92	Effect of Ag Addition on the Ripening Growth of $\{m \text{ Cu} \}_6 \{m \text{ Sn} \}_5$ Grains at the Interface of Sn-xAg-0.5Cu/Cu During a Reflow. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1939-1946.	2.5	11
93	Investigation of various photo-patternable adhesive materials and their processing conditions for MEMS sensor wafer bonding. , 2011, , .		5
94	Study on the thermal cycle and drop test reliability of system-in-packages with an Embedded die. , 2011, , .		0
95	Effects of bonding parameters and ACF material properties on the ACF joint morphology in ultrasonic bonding. , 2011, , .		1
96	Effect of fine solder ball diameters on intermetallic growth of Sn-Ag-Cu solder at Cu and Ni pad finish interfaces during thermal aging. , 2011, , .		6
97	A study on the 3D-TSV interconnection using wafer-level non-conductive adhesives (NCAs). , 2011, , .		3
98	Effects of the Degree of Cure on the Electrical and Mechanical Behavior of Anisotropic Conductive Films. Journal of Electronic Materials, 2010, 39, 410-418.	2.2	9
99	Reduced Temperature Coefficient of Capacitance (TCC) of Embedded Capacitor Films (ECFs) for Organic Substrates using SrTiO ₃ and Multifunctional Epoxy. Journal of Electronic Materials, 2010, 39, 1358-1363.	2.2	4
100	A Study of Hygrothermal Behavior of ACF Flip Chip Packages With Moiré Interferometry. IEEE Transactions on Components and Packaging Technologies, 2010, 33, 215-221.	1.3	15
101	Effects of fine size lead-free solder ball on the interfacial reactions and joint reliability. , 2010, , .		22
102	Recent advances in anisotropic conductive adhesives (ACAs) materials and processing technology. , 2010, , .		1
103	High speed touch screen panels (TSPs) assembly using anisotropic conductive adhesives (ACAs) vertical ultrasonic bonding method. , 2010, , .		3
104	Effect of Pd addition on ultra-fine pitch Au wire/Al pad interface. , 2010, , .		7
105	Effect of Ag on ripening growth of $\text{Cu} \times 6 \text{Sn} \times 5$ grains formed between molten Sn-xAg-0.5Cu solders and Cu. , 2010, , .		3
106	Studies on various 2-metal chip-on-flex (COF) packaging methods. , 2010, , .		0
107	Photo-patternable non-conductive adhesives (NCAs) for electronic packaging applications. , 2010, , .		0
108	Thermal cycling reliability of Cu/SnAg double-bump flip chip assemblies for 100µm pitch applications. Journal of Applied Physics, 2009, 105, .	2.5	9

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109	Effects of epoxy and rubber addition on die attach films (DAFs) materials properties. , 2009, , .		3
110	Bumpless Ball Grid Array (BBGA) package using a solder resist cavity. , 2009, , .		1
111	Characterization of epoxy/BaTiO ₃ composite embedded capacitors for high frequency behaviors. , 2009, , .		3
112	Patterning of wafer level applied non-conductive adhesives (NCAs) for camera image sensor (CIS) modules. , 2009, , .		0
113	Effects of fine size lead-free solder ball on the interfacial reactions and joint reliability. , 2009, , .		2
114	Embedded chip-in-flex (CIF) packages using wafer level package (WLP) with pre-applied anisotropic conductive films (ACFs). , 2009, , .		6
115	Effects of Heating Rate on Material Properties of Anisotropic Conductive Film (ACF) and Thermal Cycling Reliability of ACF Flip Chip Assembly. IEEE Transactions on Components and Packaging Technologies, 2009, 32, 339-346.	1.3	5
116	Ultrasonic Bonding Using Anisotropic Conductive Films (ACFs) for Flip Chip Interconnection. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 241-247.	1.4	19
117	Reliability enhancement of embedded capacitors in printed circuit boards using B-stage epoxy/BaTiO ₃ composite embedded capacitor films (ECFs). , 2009, , .		0
118	The effects of the degree of cure of anisotropic conductive films (ACFs) on the contraction stress build-up of ACFs and ACF joints stability for chip-on-flex (COF) applications. , 2009, , .		4
119	20 µm-pitch complaint-bump-bonded chip-on-flex by pre-applied wafer level adhesives. , 2009, , .		0
120	Nonconductive Films (NCFs) With Multifunctional Epoxies and Silica Fillers for Reliable NCFs Flip Chip on Organic Boards (FCOBs). IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 65-73.	1.4	4
121	Effects of Anisotropic Conductive Film Viscosity on ACF Fillet Formation and Chip-On-Board Packages. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 74-80.	1.4	17
122	Adhesion and Reliability of Anisotropic Conductive Films (ACFs) Joints on Organic Solderability Preservatives (OSPs) Metal Surface Finish. Journal of Electronic Materials, 2008, 37, 1003-1011.	2.2	9
123	A Study on the Thermal Reliability of Cu/SnAg Double-Bump Flip-Chip Assemblies on Organic Substrates. Journal of Electronic Materials, 2008, 37, 1832-1842.	2.2	15
124	Theoretical Prediction and Experimental Measurement of the Degree of Cure of Anisotropic Conductive Films (ACFs) for Chip-On-Flex (COF) Applications. Journal of Electronic Materials, 2008, 37, 1580-1590.	2.2	13
125	Screen printable epoxy/BaTiO ₃ embedded capacitor pastes with high dielectric constant for organic substrate applications. Journal of Applied Polymer Science, 2008, 110, 798-807.	2.6	30
126	Fabrication and characterization of epoxy/BaTiO ₃ composite embedded capacitor for high frequency behaviors. , 2008, , .		0

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127	Effects of Thermal Cycling on Material Properties of Nonconductive Pastes (NCPs) and the Relationship Between Material Properties and Warpage Behavior During Thermal Cycling. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 559-565.	1.3	5
128	A Novel Anisotropic Conductive Film (ACF) Bonding Method Using Vertical Ultrasonic Vibration. , 2008, , .		1
129	Fabrication and characterization of embedded capacitors in printed circuit boards using B-stage epoxy/BaTiO ₃ composite embedded capacitor films (ECFs). , 2008, , .		3
130	The effects of the degree of cure of anisotropic conductive films (ACFs) on the contraction stress build-up of ACFs and ACF joints stability for ACF flip-chip interconnection. , 2008, , .		0
131	Wafer level packages (WLPs) using anisotropic conductive adhesives (ACAs) solution for flip-chip interconnections. , 2008, , .		8
132	Wafer Level ACA Packages and their Applications to Advanced Electronic Packaging. , 2008, , .		2
133	Studies on the Thermal Cycling Reliability of Fine Pitch Cu/SnAg Double-Bump Flip Chip Assemblies on Organic Substrates: Experimental Results and Numerical Analysis. , 2008, , .		1
134	Thermal stability at the anisotropic conductive films (ACFs)/ organic solderability preservatives (OSPs) Interface. , 2007, , .		0
135	Thermal cycling reliability of Cu/SnAg double-bump flip-chip assemblies for 100um pitch applications. , 2007, , .		1
136	Effects of anisotropic conductive film (ACF) viscosity on ACF fillet and moisture-related reliability for flip-chip-on-board (FCOB) packages. , 2007, , .		0
137	Effects of the Functional Groups of Nonconductive Films (NCFs) on Material Properties and Reliability of NCF Flip-Chip-On-Organic Boards. IEEE Transactions on Components and Packaging Technologies, 2007, 30, 464-471.	1.3	11
138	Effects of Heating Rate During ACFs Curing Process on Material Properties and Thermal Cycling Reliability of Flip Chip Assembly. , 2007, , .		0
139	Fabrication and characterization of Epoxy/BaTiO ₃ composite capacitor films for high frequency behaviors. , 2007, , .		0
140	Theoretical prediction and experimental measurement of the degree-of-cure of anisotropic conductive film (ACF) for chip-on-flex (COF) applications. , 2007, , .		0
141	Adhesion and Reliability of Anisotropic Conductive Films (ACFs) Joints on Organic Solderability Preservatives (OSPs) Metal Surface Finish. , 2007, , .		1
142	Wafer-Level Flip Chip Packages Using Preapplied Anisotropic Conductive Films (ACFs). IEEE Transactions on Electronics Packaging Manufacturing, 2007, 30, 221-227.	1.4	14
143	Room temperature ACF bonding process using ultrasonic vibration for chip-on-board and flex-on-board applications. , 2007, , .		0
144	Effect of Sb addition in Sn-Ag-Cu solder balls on the drop test reliability of BGA packages with electroless nickel immersion gold (ENIG) surface finish. , 2007, , .		2

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145	Non-Conductive Films (NCFs) with Multi-Functional Epoxies and Silica Fillers for Reliable NCFs Flip Chip On Organic Boards (FCOB). , 2007, , .		2
146	Effect of electroless Ni/Au UBM thickness on mechanical and electromigration reliability of Pb-free solder joints. , 2007, , .		1
147	Electromigration of Pb-Free Solder Flip Chip Using Electroless Ni-P/Au UBM. , 2007, , .		7
148	Cu/SnAg Double Bump Flip Chip Assembly as an Alternative of Solder Flip Chip on Organic Substrates for Fine Pitch Applications. , 2007, , .		13
149	Wafer Level Packages (WLPs) using Pre-Applied Anisotropic Conductive Films (ACFs). , 2007, , .		5
150	Study of the Formation of Bubbles in Rigid Substrate-Flexible Substrate Bonding Using Anisotropic Conductive Films and the Bubble Effects on Anisotropic Conductive Film Joint Reliability. Journal of Electronic Materials, 2007, 36, 56-64.	2.2	7
151	Multi-functional epoxy/SrTiO ₃ /sub 3/ ceramic powder embedded capacitor films(ECFs) for organic substrates. , 2006, , .		1
152	Novel Non-Conductive Films(NCFs) with Multi-Functional Epoxies and Silica Fillers for Reliable NCFs Flip-Chip-On-Organic Boards. , 2006, , .		0
153	Epoxy/BaTiO ₃ (SrTiO ₃) Composite Films and Pastes For High Dielectric Constant and Low Tolerance Embedded Capacitors in Organic Substrates. , 2006, , .		12
154	Electromigration of Pb-free solder flip chip using electroless Ni-P/Au UBM. , 2006, , .		0
155	Effect of electromigration on mechanical shear behavior of flip chip solder joints. Journal of Materials Research, 2006, 21, 698-702.	2.6	27
156	Effects of metal surface finish on the anisotropic conductive adhesives (ACAs) joints. , 2006, , .		0
157	Effects of Cu contents in Pb-free solder alloys on interfacial reactions and bump reliability of Pb-free solder bumps on electroless Ni-P under-bump metallurgy. Journal of Electronic Materials, 2005, 34, 80-90.	2.2	38
158	A study on the temperature dependence of epoxy/BaTiO ₃ composite embedded capacitor films. Journal of Electronic Materials, 2005, 34, 1264-1269.	2.2	10
159	Comparison of theoretical predictions and experimental values of the dielectric constant of epoxy/BaTiO ₃ composite embedded capacitor films. Journal of Materials Science: Materials in Electronics, 2005, 16, 77-84.	2.2	86
160	Frequency and Temperature Dependence of Dielectric Constant of Epoxy/BaTiO ₃ Composite Embedded Capacitor Films (ECFs) for Organic Substrate. , 2005, , .		12
161	Flip chip interconnection with anisotropic conductive adhesives for RF and high-frequency applications. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 789-796.	1.3	33
162	Epoxy/BaTiO ₃ /sub 3/ composite films and pastes for high dielectric constant and low-tolerance embedded capacitors fabrication in organic substrates. IEEE Transactions on Electronics Packaging Manufacturing, 2005, 28, 297-303.	1.4	19

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163	Effects of Pd addition on Au stud bumps/Al pads interfacial reactions and bond reliability. Journal of Electronic Materials, 2004, 33, 1210-1218.	2.2	27
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